

# LNJ214R8ARA

## Surface Mounting Chip LED

### USS Type

#### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	40	mW
Forward current	$I_F$	15	mA
Pulse forward current *	$I_{FP}$	50	mA
Reverse voltage	$V_R$	3	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

#### ■ Lighting Color

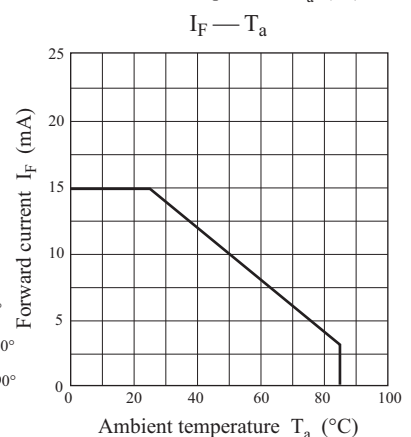
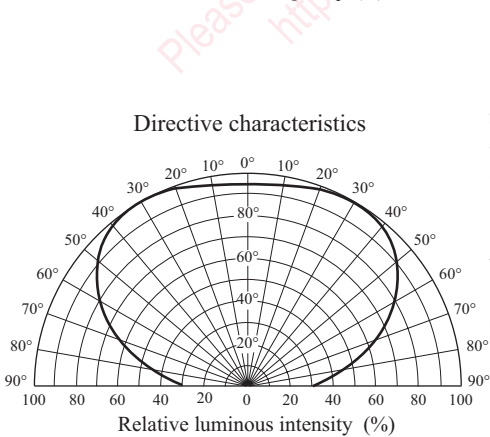
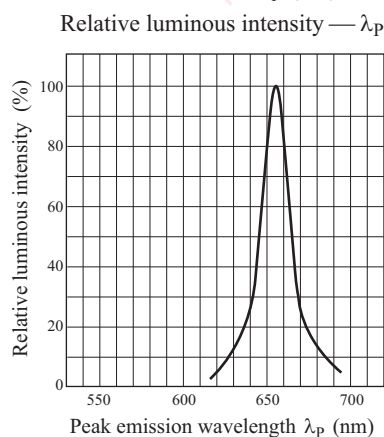
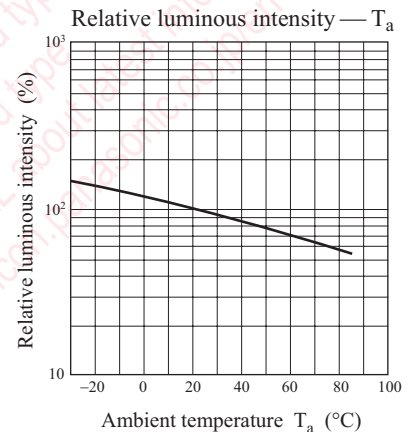
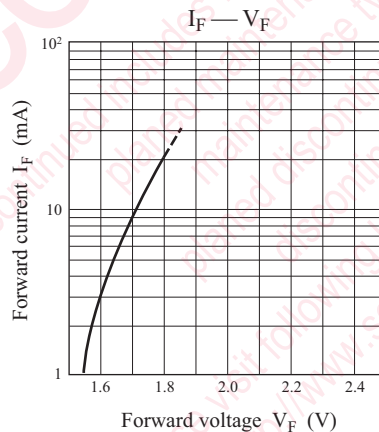
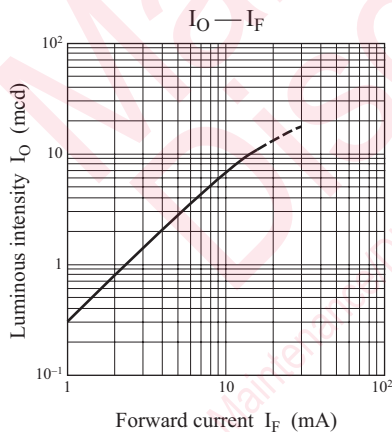
- Red

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

#### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	$I_O$	$I_F = 10\text{ mA}$	2.75	6.7		mcd
Reverse current	$I_R$	$V_R = 3\text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		1.72	2.5	V
Peak emission wavelength	$\lambda_P$	$I_F = 10\text{ mA}$		655		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		20		nm

Note) \*: Measurement tolerance:  $\pm 20\%$

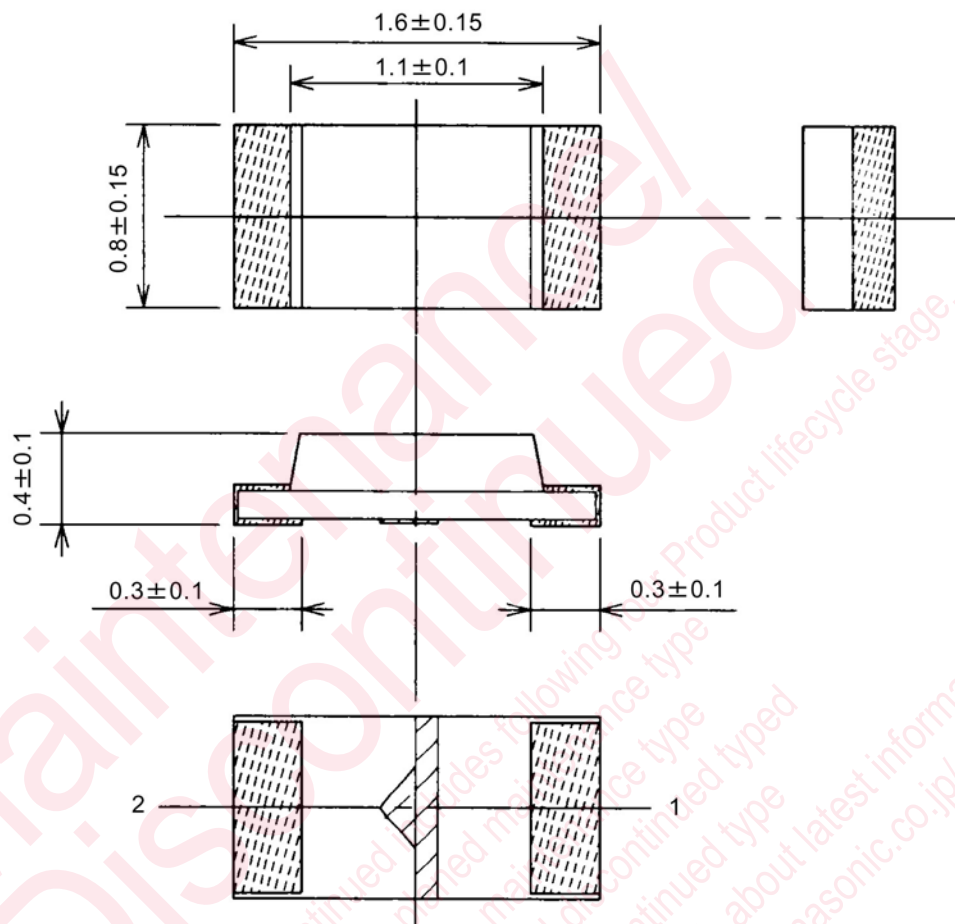


LNJ214R8ARA

**Panasonic**

■ Package (Unit: mm)

KLTFTN2K1400



- Pin name
- 1: Anode
- 2: Cathode

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